

**In the claims:**

1. (previously presented) A method and system of wire bonding a semiconductor die to a lead, comprising the steps of:

attaching a first end of a first bonding wire to a semiconductor die with a ball bond;

attaching a second end of the first bonding wire to an interposer pad with a stitch bond;

attaching a first end of a second bonding wire to the interposer pad with a ball bond; and

attaching the second end of the second bonding wire to the lead with a stitch bond.

2. (previously presented) The method and system of wire bonding a semiconductor die to a lead as recited in Claim 1, wherein the first bonding wire and second bonding wire are made of a gold-based material.

3-4. (canceled)

5. (previously presented) The method and system of wire bonding a semiconductor die to a lead as recited in Claim 1, wherein the interposer pad has x-y dimensions of between approximately 58 micrometers to 88 micrometers along an x-axis and 88 micrometers along a y-axis.

6. (previously presented) The method and system of wire bonding a semiconductor die to a lead as recited in Claim 1, for use in ball bond grid array packages.

7. (canceled)

8. (previously presented) A semiconductor device comprising:  
a semiconductor die disposed on a substrate;  
a plurality of interposer pads on said substrate;  
a plurality of leads on the substrate;  
a plurality of bonding wires attached to the semiconductor die with ball bonds and to the leads with stitch bonds, said wires attached to said interposer pads.

9. (previously presented) The semiconductor device as recited in Claim 8, wherein the plurality of bonding wires are comprised of gold-based material.

10. (canceled)

11. (previously presented) The semiconductor device as recited in Claim 8, wherein each of said bonding wires comprises a bonding wire between the semiconductor die and each interposer pad attached to a bonding pad on the semiconductor die with a ball bond and to said interposer pad with a stitch bond and a bonding wire between the interposer pad and the lead attached to the interposer pad with a ball bond and to each lead with a stitch bond.

12. (previously presented) The semiconductor device as recited in Claim 8, wherein the interposer pads are dimensioned from 58 micrometers to 88 micrometers along an x-axis and from 88 to 125 micrometers along a y-axis.

13. (previously presented) The semiconductor device as recited in Claim 8, wherein the semiconductor package comprises a ball grid array.

14. (canceled)

15. (previously presented) The semiconductor device as recited in Claim 8 wherein an interposer pad electrically floats on the substrate.

16. (previously presented) A method of fabricating a semiconductor device, comprising:

attaching a semiconductor die to a substrate having a plurality of leads and a plurality of interposer pads arranged around said die;

coupling the die to the plurality of interposer pads with a first plurality of bonding wires ball bonded to said die and stitch bonded to said interposer pads; and

coupling the plurality of interposer pads to the plurality of leads with a second plurality of bonding wires ball bonded to said interposer pads and stitch bonded to said leads.

17. (previously presented) The method of fabricating a semiconductor device as recited in Claim 16, wherein the plurality of interposer pads electrically float on the semiconductor package.

18. (previously presented) The method of fabricating a semiconductor device as recited i Claim 16, wherein the plurality of interposer pads electrically float on the semiconductor package.

19. (canceled) The method of fabricating a semiconductor device as recited i Claim 16, wherein the semiconductor package interposer pads are fabricated on an elector-less substrate.

20. (previously presented) The method of fabricating a semiconductor device as recited i Claim 16, wherein the placement of the interposer pads are are operable to reduce wire sweep.

21. (previously presented) The method of fabricating a semiconductor device as recited i Claim 16, wherein the semiconductor package comprises a ball grid array.

22. (canceled)